Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPU60R2K0C6	Issued	29. September 2015
MA#	MA001402334		
Package	PG-TO251-3-341	Weight*	387.39 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.272	0.33	0.33	3282	3282
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		641	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		192	
	non noble metal	copper	7440-50-8	248.124	64.06	64.14	640508	641341
wire	non noble metal	aluminium	7429-90-5	0.441	0.11	0.11	1138	1138
encapsulation	organic material	carbon black	1333-86-4	0.394	0.10		1017	
	plastics	epoxy resin	-	11.948	3.08		30843	
	inorganic material	silicondioxide	60676-86-0	118.957	30.71	33.89	307076	338936
leadfinish	non noble metal	tin	7440-31-5	3.787	0.98	0.98	9775	9775
plating	non noble metal	nickel	7440-02-0	0.515	0.13	0.13	1330	1330
solder	noble metal	silver	7440-22-4	0.041	0.01		105	
	non noble metal	tin	7440-31-5	0.033	0.01		84	
	non noble metal	lead	7439-92-1	1.553	0.40	0.42	4009	4198
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com